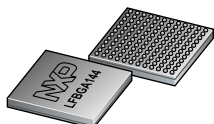


SOT2134-1

LFBGA144, low-profile fine-pitch ball grid array package, 144 terminals, 0.8 mm pitch, 10 mm x 10 mm x 1.37 mm body

4 July 2025

Package information



1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA144
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Mounting method type	S (surface mount)
Issue date	30-03-2021
Manufacturer package code	98ASA01754D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	9.85	10	10.15	mm
package width	9.85	10	10.15	mm
package height	-	1.37	1.52	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	144	-	

LFBGA144, low-profile fine-pitch ball grid array package, 144 terminals, 0.8 mm pitch, 10 mm x 10 mm x 1.37 mm body

2 Package outline

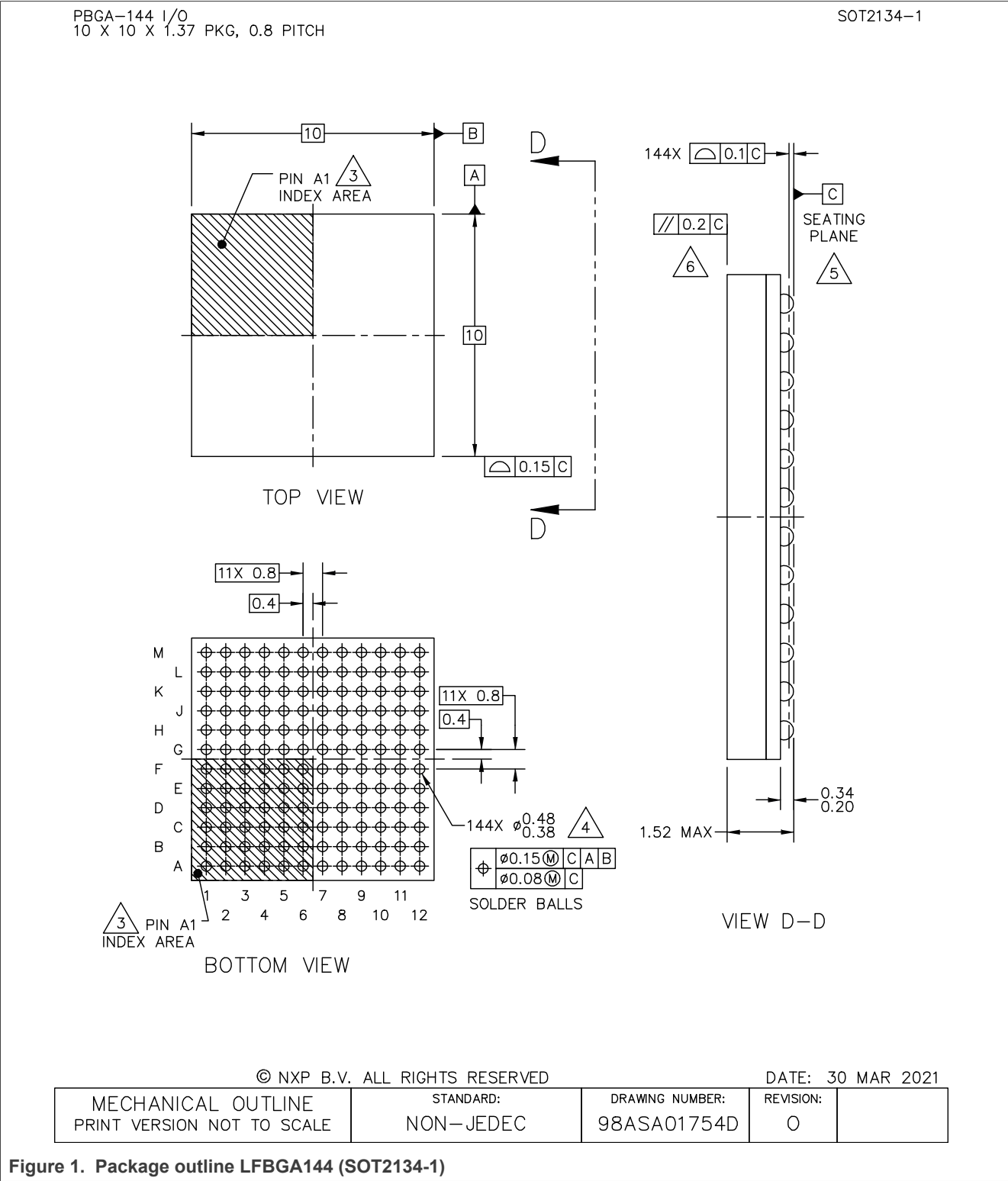
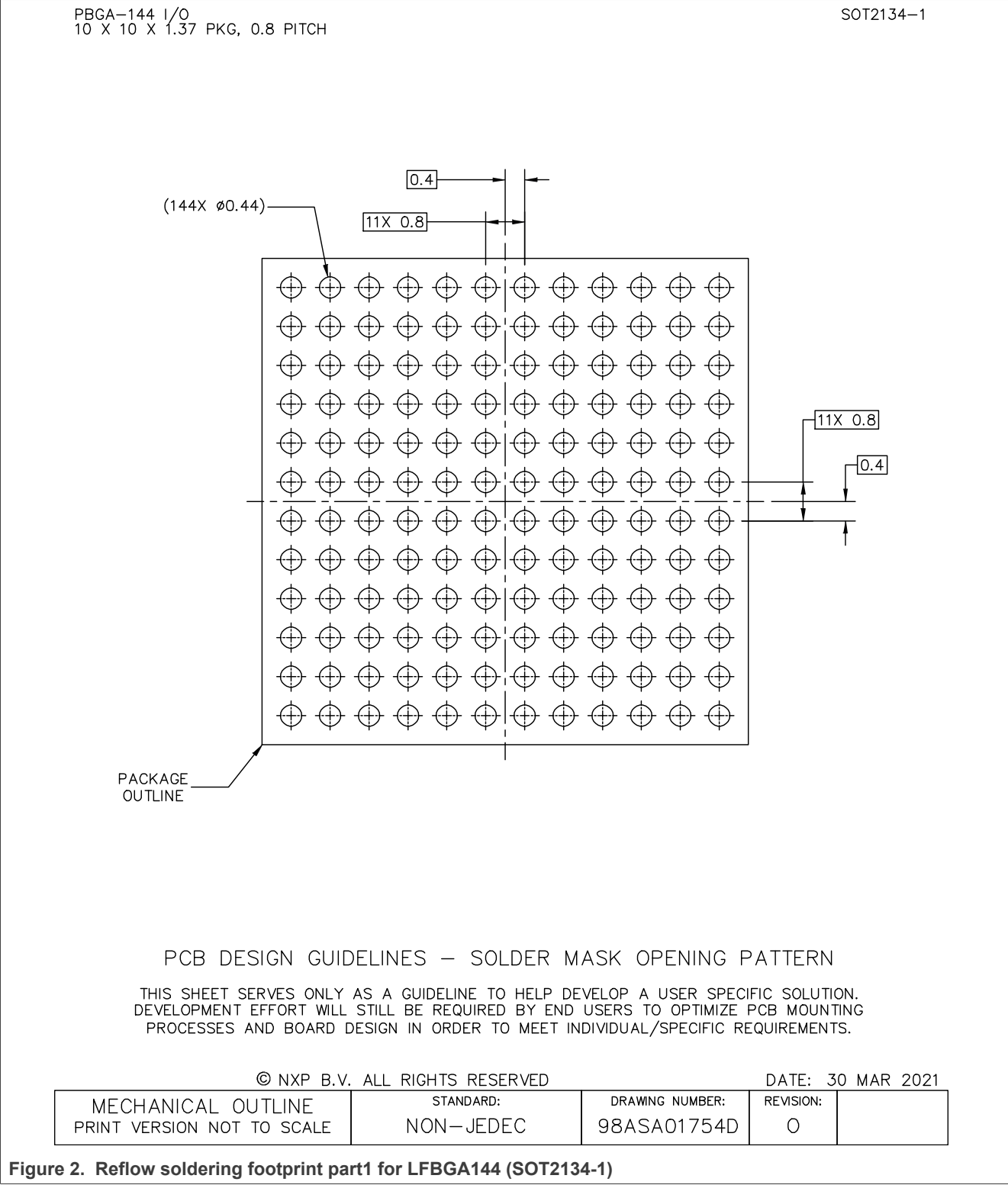


Figure 1. Package outline LFBGA144 (SOT2134-1)

LFBGA144, low-profile fine-pitch ball grid array package, 144 terminals, 0.8 mm pitch, 10 mm x 10 mm x 1.37 mm body

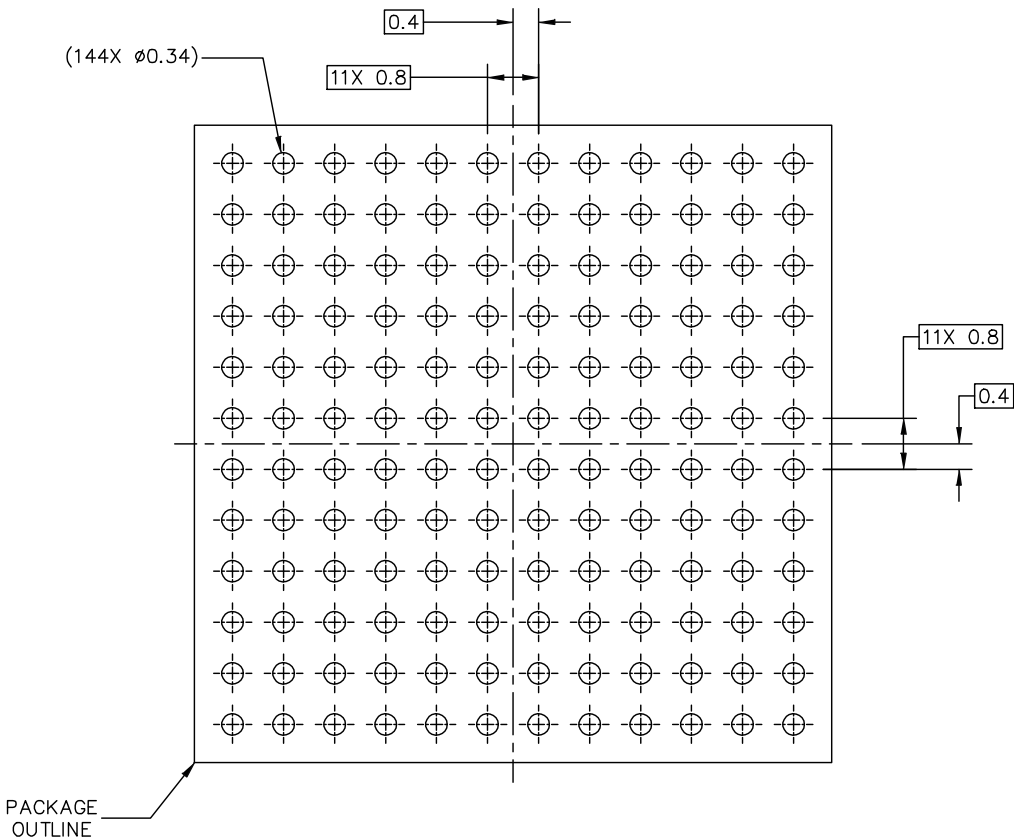
3 Soldering



LFBGA144, low-profile fine-pitch ball grid array package, 144 terminals, 0.8 mm pitch, 10 mm x 10 mm x 1.37 mm body

PBGA-144 I/O
10 X 10 X 1.37 PKG, 0.8 PITCH

SOT2134-1



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION.
DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING
PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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DATE: 30 MAR 2021

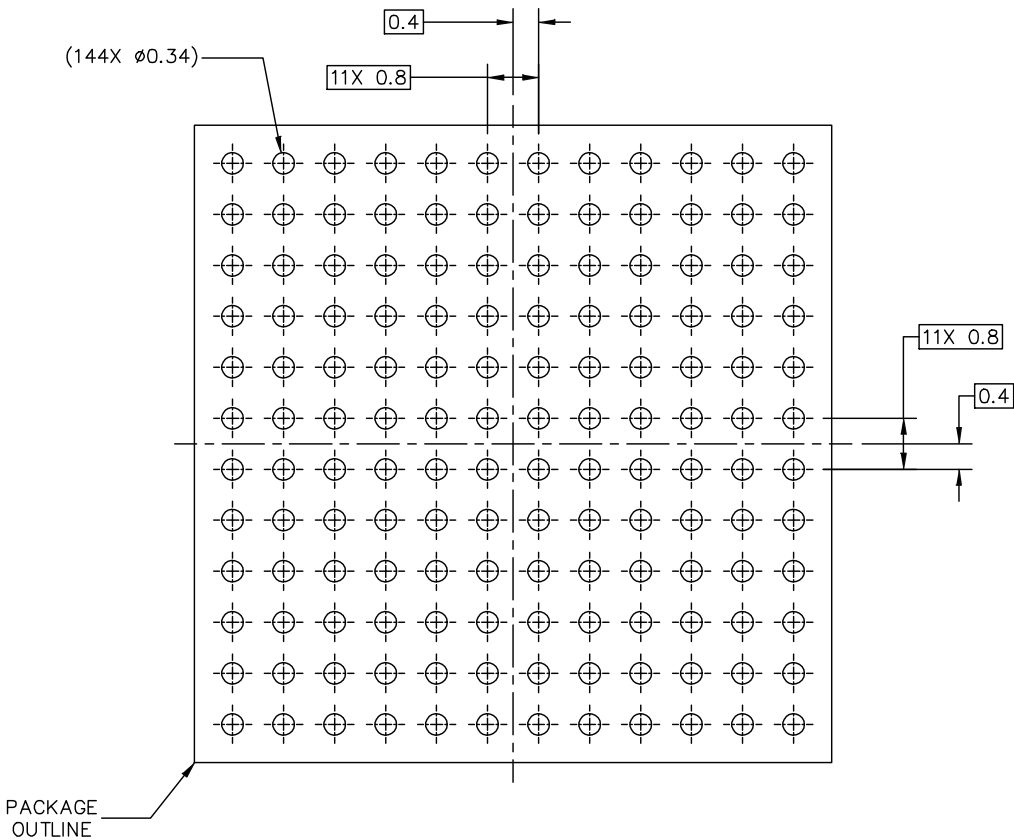
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01754D	REVISION: O	
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Figure 3. Reflow soldering footprint part2 for LFBGA144 (SOT2134-1)

LFBGA144, low-profile fine-pitch ball grid array package, 144 terminals, 0.8 mm pitch, 10 mm x 10 mm x 1.37 mm body

PBGA-144 I/O
10 X 10 X 1.37 PKG, 0.8 PITCH

SOT2134-1



RECOMMENDED STENCIL THICKNESS 0.125 MM

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01754D	REVISION: 0	
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Figure 4. Reflow soldering footprint part3 for LFBGA144 (SOT2134-1)

LFBGA144, low-profile fine-pitch ball grid array package, 144 terminals, 0.8 mm pitch, 10 mm x 10 mm x 1.37 mm body

PBGA-144 I/O
10 X 10 X 1.37 PKG, 0.8 PITCH

SOT2134-1

NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
- 5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01754D	REVISION: 0

Figure 5. Package outline note LFBGA144 (SOT2134-1)

4 Legal information

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LFBGA144, low-profile fine-pitch ball grid array package, 144 terminals, 0.8 mm pitch, 10 mm x 10 mm x 1.37 mm body

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